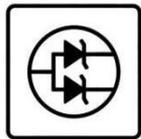


MSKSEMI 美森科

SEMICONDUCTOR



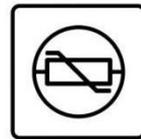
ESD



TVS



TSS



MOV



GDT



PLED

AZC199-02S-MS

Product specification

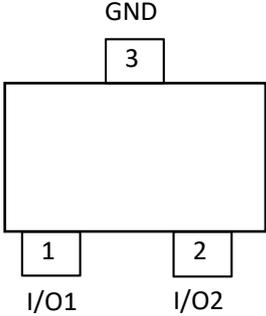
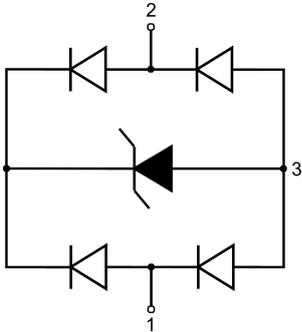
Features

- Stand-off voltage: 5V Max
- Transient protection for each line according to IEC61000-4-2 (ESD): $\pm 20\text{kV}$ (contact and air discharge)
IEC61000-4-4 (EFT): 40A (5/50ns)
IEC61000-4-5 (surge): 4A (8/20 μs)
- Ultra-low capacitance: $C_J = 0.4\text{pF}$ typ.
- Ultra-low leakage current: $I_R < 1\text{nA}$ typ.
- Low clamping voltage: $V_{CL} = 20\text{V}$ @ $I_{PP} = 16\text{A}$ (TLP)
- Solid-state silicon technology

Application

- USB 2.0 and USB 3.0
- HDMI 1.3 and HDMI 1.4
- SATA and eSATA
- DVI
- IEEE 1394
- PCI Express
- Portable Electronics
- Notebooks

Reference News

PACKAGE OUTLINE	Circuit diagram	Pin Configuration	Marking
			
SOT-23			

Absolute Maximum Ratings (Tamb=25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Peak pulse power ($t_p = 8/20\mu s$)	P_{pk}	60	W
Peak pulse current ($t_p = 8/20\mu s$)	I_{PP}	4	A
ESD according to IEC61000-4-2 air discharge	V_{ESD}	± 20	kV
ESD according to IEC61000-4-2 contact discharge		± 20	
Junction temperature	T_J	125	°C
Operating temperature	T_{OP}	-40~85	°C
Lead temperature	T_L	260	°C
Storage temperature	T_{STG}	-55~ 150	°C

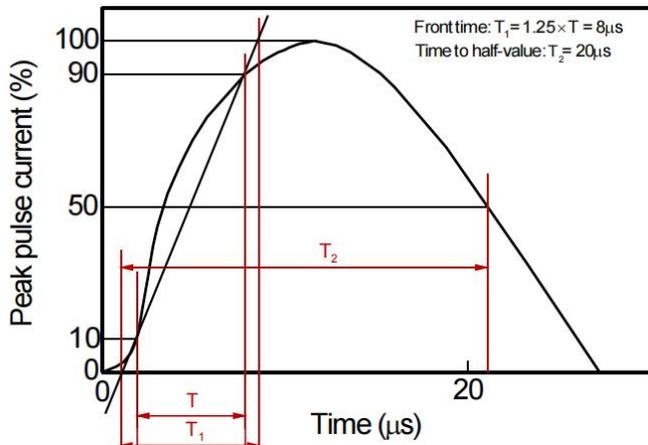
Electrical characteristics (TA=25 °C, unless otherwise noted)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse maximum working voltage	V_{RWM}				5.0	V
Reverse leakage current	I_R	$V_{RWM} = 5V$		<1	100	nA
Reverse breakdown voltage	V_{BR}	$I_T = 1mA$	7.0	8.0	9.0	V
Forward voltage	V_F	$I_T = 10mA$	0.6	0.9	1.2	V
Clamping voltage ¹⁾	V_{CL}	$I_{PP} = 16A, t_p = 100ns$		20		V
Dynamic resistance ¹⁾	R_{DYN}			0.65		Ω
Clamping voltage ²⁾	V_{CL}	$I_{PP} = 1A, t_p = 8/20\mu s$			11	V
		$I_{PP} = 4A, t_p = 8/20\mu s$			15	V
Junction capacitance	C_J	$V_R = 0V, f = 1MHz$ Any I/O pin to GND		0.40	0.65	pF
		$V_R = 0V, f = 1MHz$ Between any I/O pin		0.25	0.40	pF

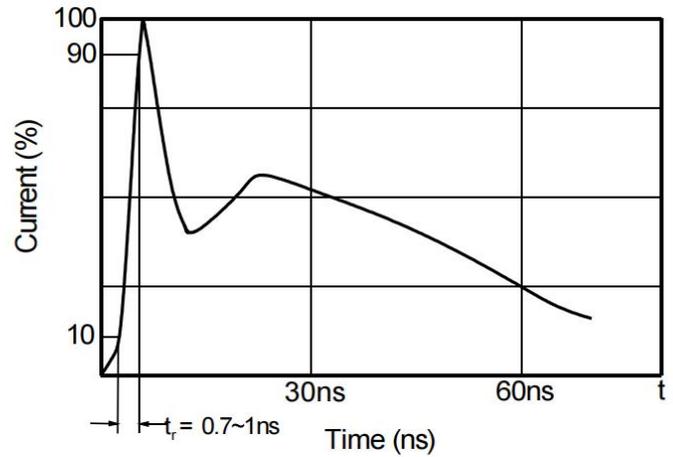
Notes:

- 1) TLP parameter: $Z_0 = 50 \Omega$, $t_p = 100ns$, $t_r = 2ns$, averaging window from 60ns to 80ns. RDYN is calculated from 4A to 16A.
- 2) According to IEC61000-4-5.

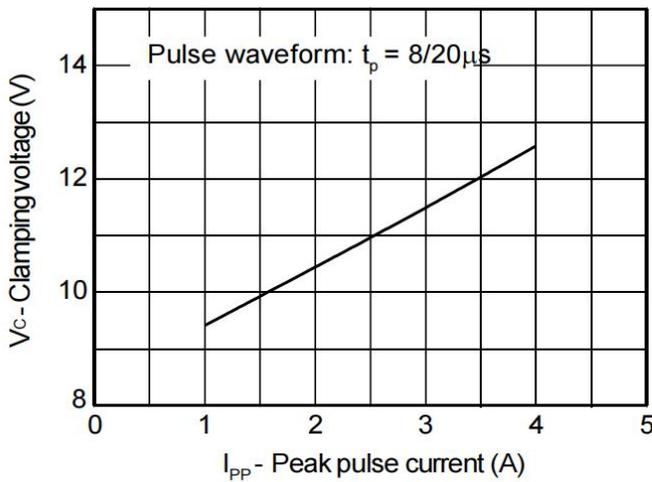
Typical characteristics (TA=25 oC, unless otherwise noted)



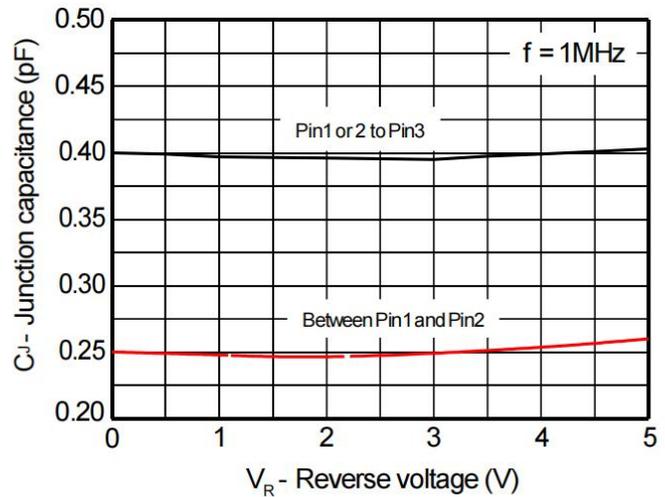
8/20μs waveform per IEC61000-4-5



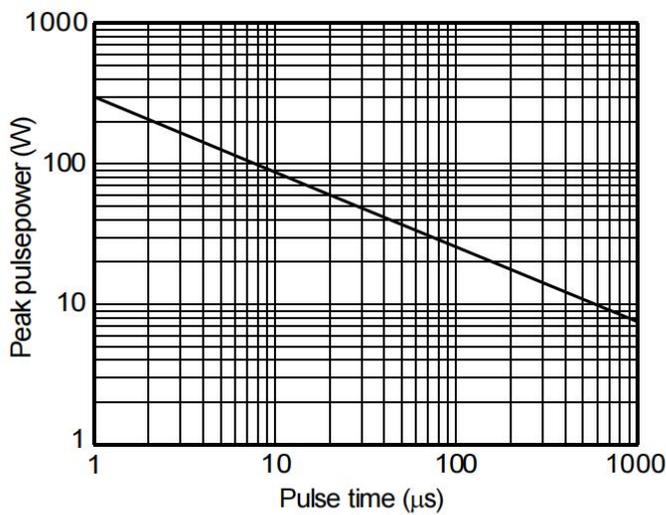
Contact discharge current waveform per IEC61000-4-2



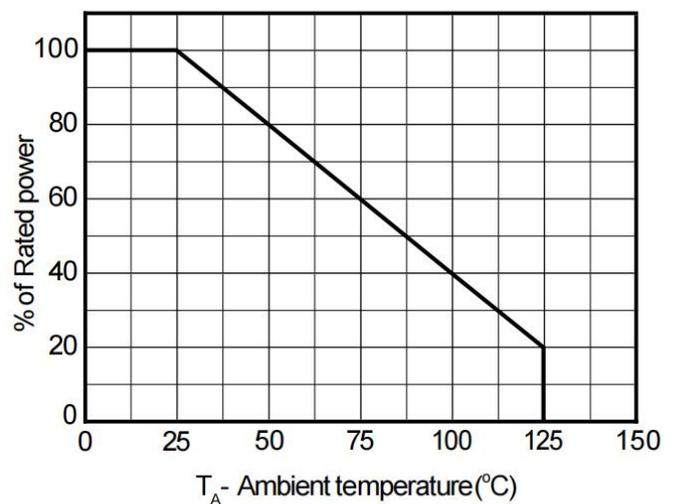
Clamping voltage vs. Peak pulse current



Capacitance vs. Reverse voltage

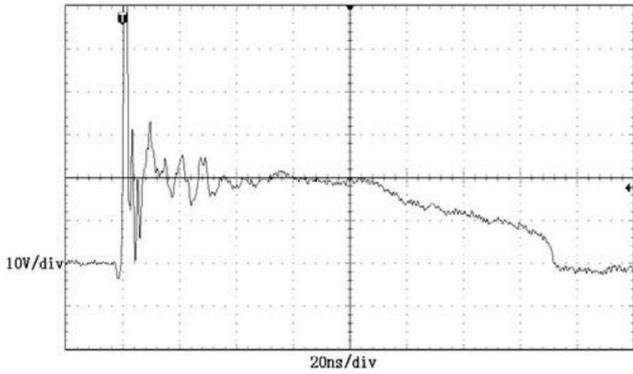


Non-repetitive peak pulse power vs. Pulse time

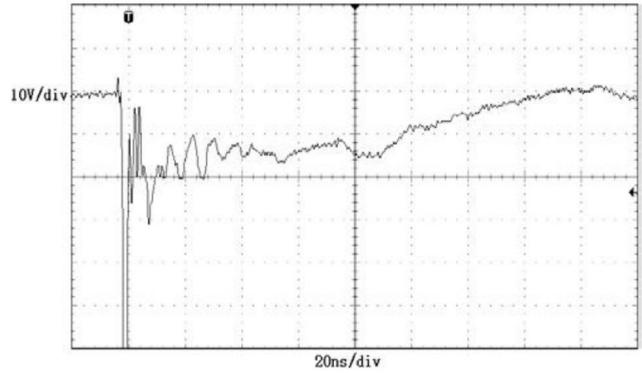


Power derating vs. Ambient temperature

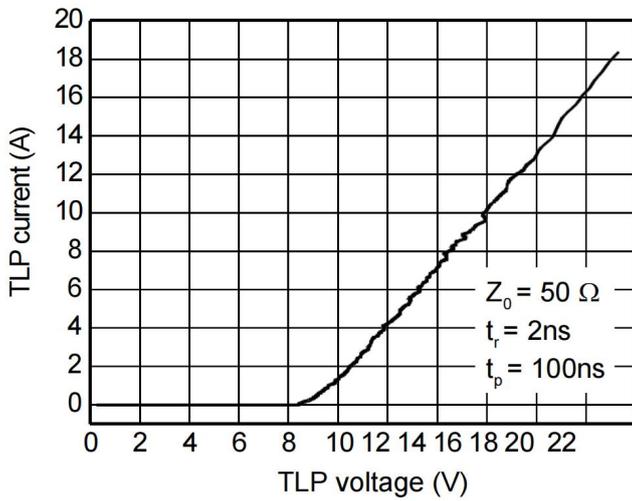
Typical characteristics (TA=25 oC, unless otherwise noted)



ESD clamping
(+8kV contact discharge per IEC61000-4-2)

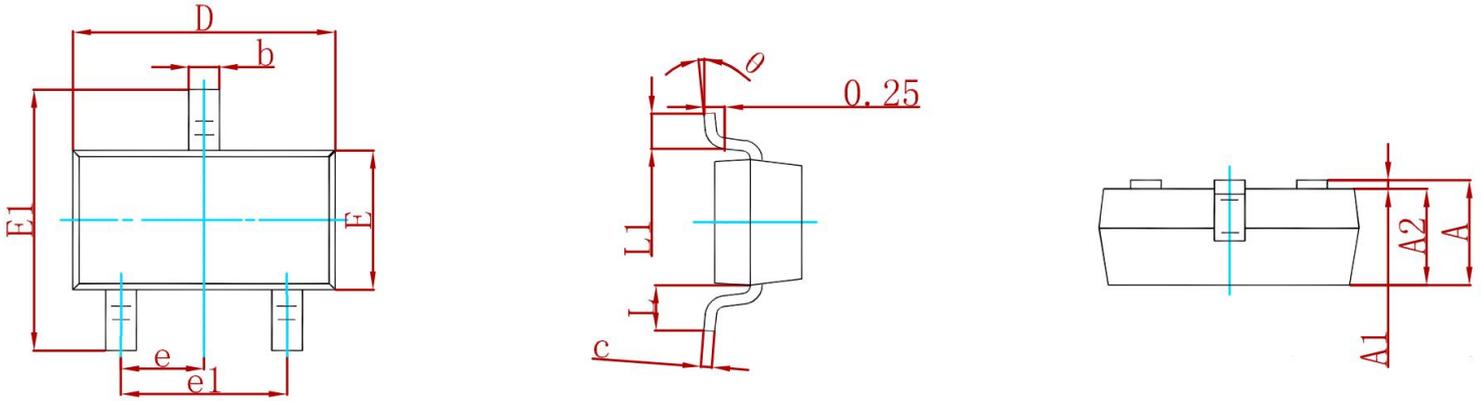


ESD clamping
(-8kV contact discharge per IEC61000-4-2)



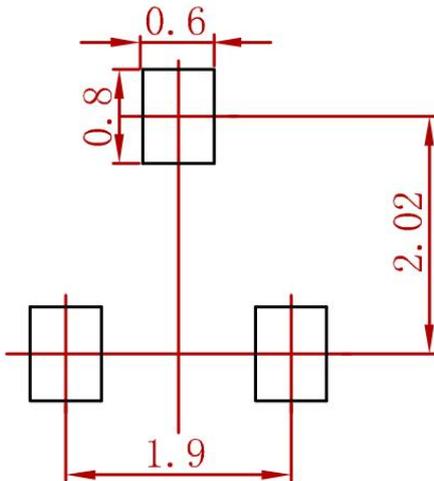
TLP Measurement

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
AZC199-02S-MS	SOT-23	3000

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